

Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- Halogen free package
- JEDEC Qualification
- Fast reverse recovery

$$V_{DSS} = 550 \text{ V @ } T_{jmax}$$

$$I_D = 11 \text{ A}$$

$$R_{DS(ON)} = 0.67 \text{ (max) @ } V_{GS} = 10 \text{ V}$$

Absolute Maximum Ratings

Parameter	Symbol	TMP11N50(G)	TMPF11N50(G)	Unit
Drain-Source Voltage	V_{DSS}	500		V
Gate-Source Voltage	V_{GS}	±30		V
Continuous Drain Current	$T_C = 25 \text{ }^\circ\text{C}$	11	11 *	A
	$T_C = 100 \text{ }^\circ\text{C}$	6	6 *	A
Pulsed Drain Current (Note 1)	I_{DM}	44	44*	A
Single Pulse Avalanche Energy (Note 2)	E_{AS}	544		mJ
Repetitive Avalanche Current (Note 1)	I_{AR}	11		A
Repetitive Avalanche Energy (Note 1)	E_{AR}	15.8		mJ
Power Dissipation	$T_C = 25 \text{ }^\circ\text{C}$	158	51.4	W
	Derate above 25 °C	1.26	0.41	W/°C
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5		V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150		°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	300		°C

Thermal Characteristics

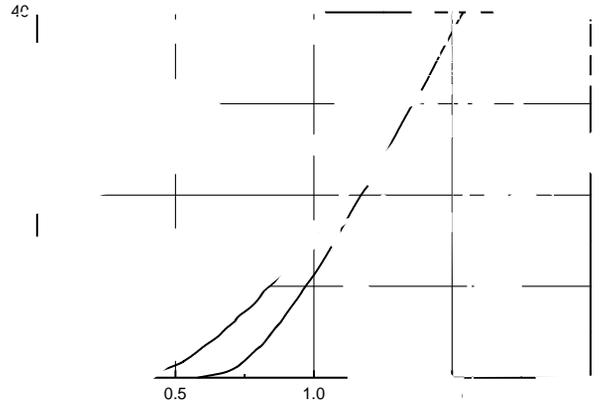
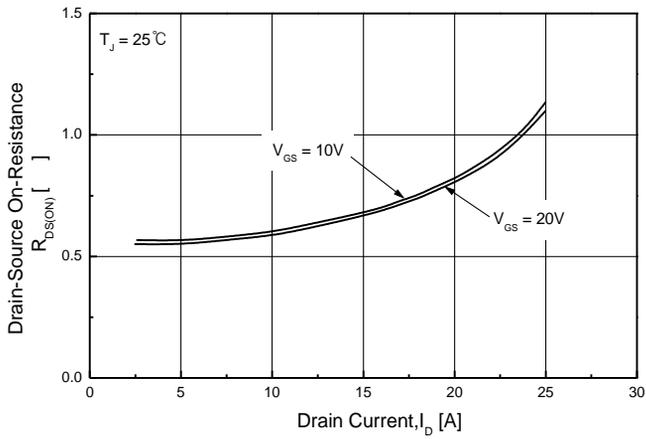
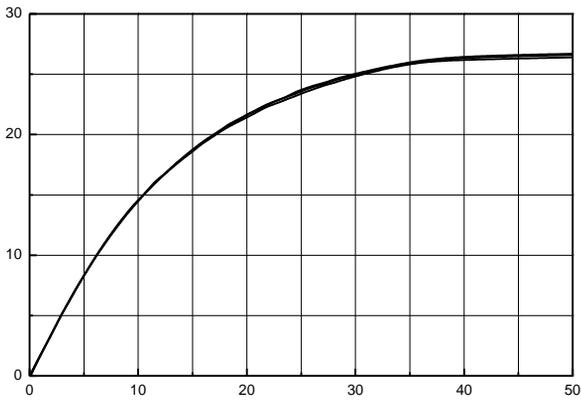
Parameter	Symbol			

Electrical Characteristics : $T_C=25^\circ\text{C}$, unless otherwise noted

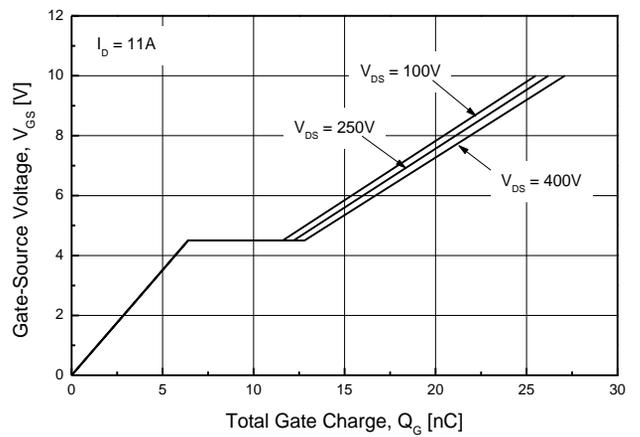
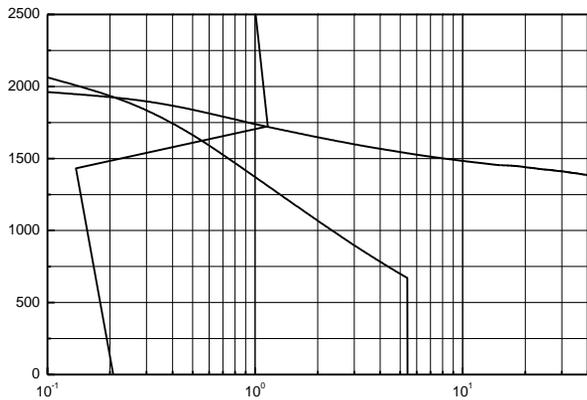
Parameter	Symbol	Test condition	Min	Typ	Max	Units
OFF						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	500	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 400\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	μA
Forward Gate-Source Leakage Current	I_{GSSF}	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
Reverse Gate-Source Leakage Current	I_{GSSR}	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

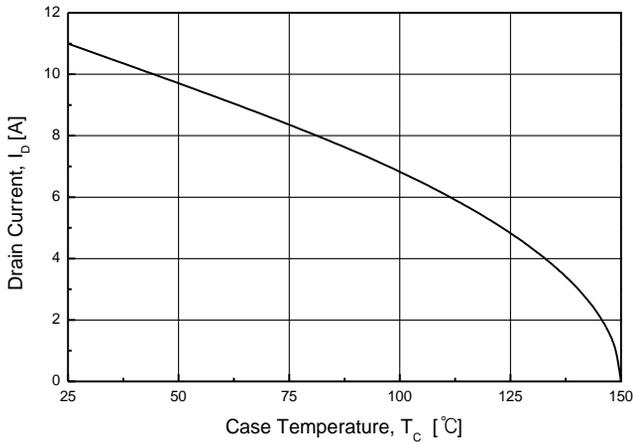
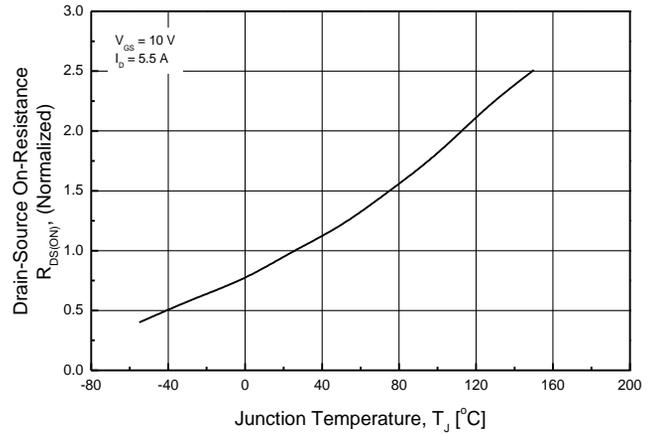
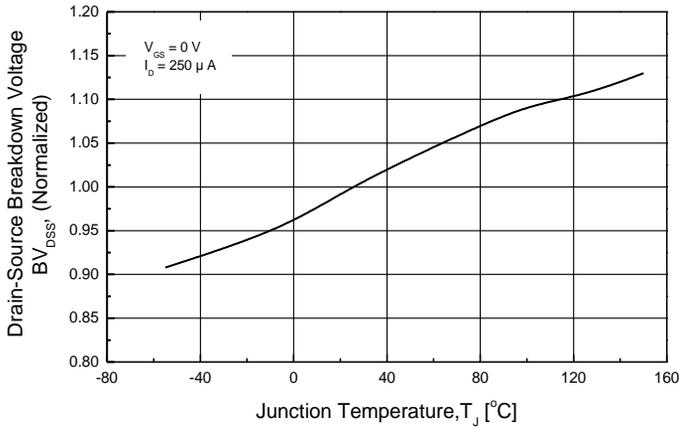
ON						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	2	--	4	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 5.5\text{ A}$	--	0.54	0.67	
Forward Transconductance ^(Note 4)	g					

- Note :
1. Repeated rating : Pulse width limited by safe operating area
 2. $L=8.1\text{mH}, I_{AS} = 11\text{A}, V_{DD} = 50\text{V}, R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$
 3. $I_{SD} = 11\text{A}, di/dt = 200\text{A}/\mu\text{s}, V_{DD} = BV_{DS}$, Starting $T_J = 25^\circ\text{C}$
 4. Pulse Test : Pulse width $300\mu\text{s}$, Duty Cycle 2%
 5. Essentially Independent of Operating Temperature Typical Characteristics

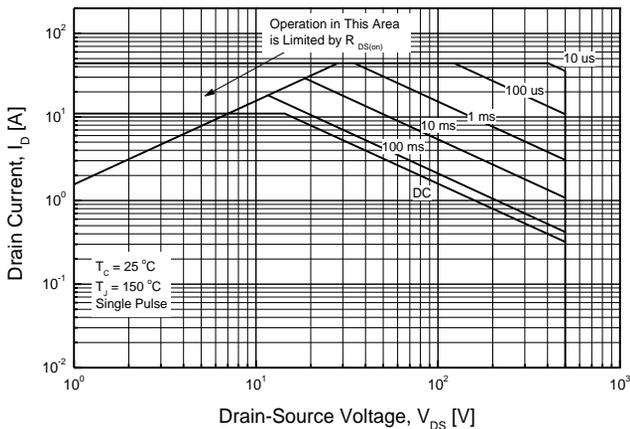


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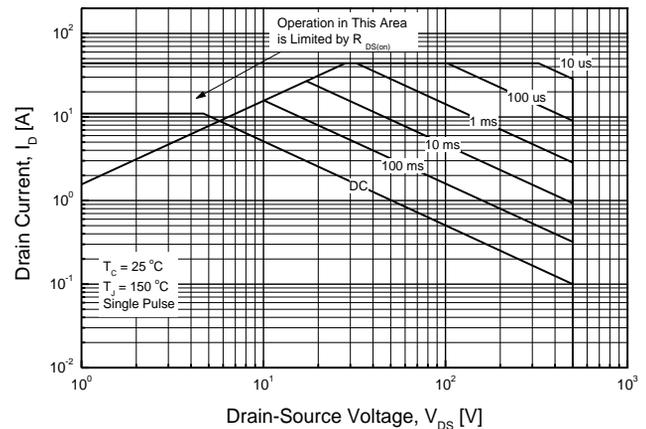




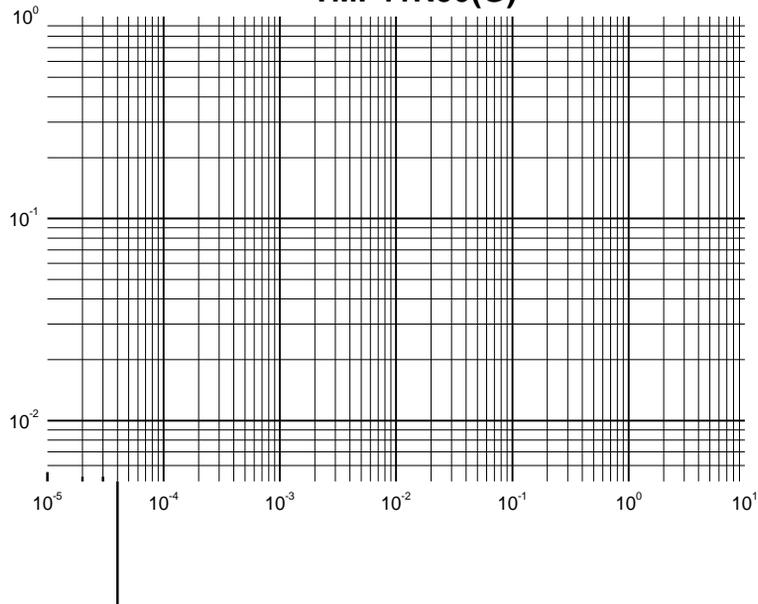
TMP11N50(G)



TMPF11N50(G)



TMP11N50(G)



TMPF11N50(G)

